

## N-channel 650 V, 0.98 $\Omega$ typ., 5 A MDmesh™ M2 Power MOSFET in a DPAK package

Datasheet - production data

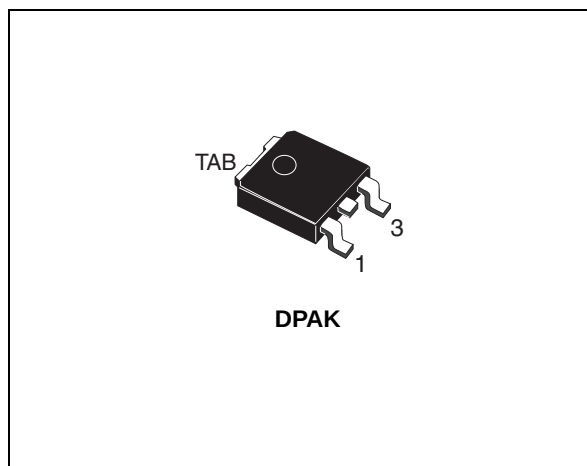
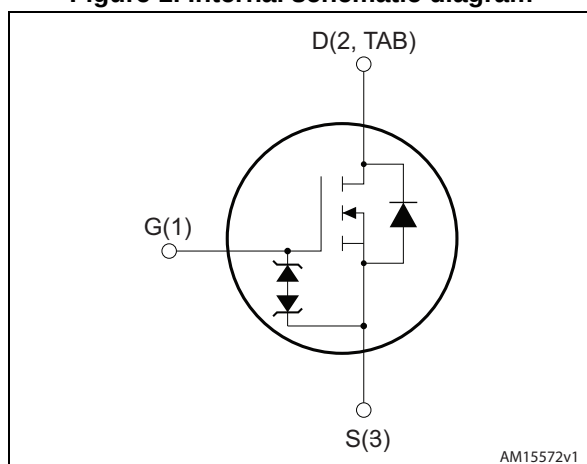


Figure 1. Internal schematic diagram



### Features

| Order code | $V_{DS}$ | $R_{DS(on)max}$ | $I_D$ |
|------------|----------|-----------------|-------|
| STD7N65M2  | 650 V    | 1.15 $\Omega$   | 5 A   |

- Extremely low gate charge
- Excellent output capacitance ( $C_{OSS}$ ) profile
- 100% avalanche tested
- Zener-protected

### Applications

- Switching applications

### Description

This device is an N-channel Power MOSFET developed using the MDmesh™ M2 technology. Thanks to the strip layout associated to an improved vertical structure, the device exhibits both low on-resistance and optimized switching characteristics. It is therefore suitable for the most demanding high efficiency converters.

Table 1. Device summary

| Order code | Marking | Package | Packaging     |
|------------|---------|---------|---------------|
| STD7N65M2  | 7N65M2  | DPAK    | Tape and reel |

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

| Symbol         | Parameter                                                         | Value       | Unit               |
|----------------|-------------------------------------------------------------------|-------------|--------------------|
| $V_{GS}$       | Gate-source voltage                                               | $\pm 25$    | V                  |
| $I_D$          | Drain current (continuous) at $T_C = 25\text{ }^{\circ}\text{C}$  | 5           | A                  |
| $I_D$          | Drain current (continuous) at $T_C = 100\text{ }^{\circ}\text{C}$ | 3.2         | A                  |
| $I_{DM}^{(1)}$ | Drain current (pulsed)                                            | 20          | A                  |
| $P_{TOT}$      | Total dissipation at $T_C = 25\text{ }^{\circ}\text{C}$           | 60          | W                  |
| $dv/dt^{(2)}$  | Peak diode recovery voltage slope                                 | 15          | V/ns               |
| $dv/dt^{(3)}$  | MOSFET $dv/dt$ ruggedness                                         | 50          |                    |
| $T_{stg}$      | Storage temperature                                               | - 55 to 150 | $^{\circ}\text{C}$ |
| $T_j$          | Operating junction temperature                                    |             |                    |

1. Pulse width limited by safe operating area
2.  $I_{SD} \leq 5\text{ A}$ ,  $di/dt \leq 400\text{ A}/\mu\text{s}$ ;  $V_{DS\text{ peak}} < V_{(BR)DSS}$ ,  $V_{DD}=400\text{ V}$
3.  $V_{DS} \leq 520\text{ V}$

**Table 3. Thermal data**

| Symbol         | Parameter                            | Value             | Unit                        |
|----------------|--------------------------------------|-------------------|-----------------------------|
| $R_{thj-case}$ | Thermal resistance junction-case max | 2.08              | $^{\circ}\text{C}/\text{W}$ |
| $R_{thj-pcb}$  | Thermal resistance junction-pcb max  | 50 <sup>(1)</sup> | $^{\circ}\text{C}/\text{W}$ |

1. When mounted on 1 inch<sup>2</sup> FR-4, 2 Oz copper board.

**Table 4. Avalanche characteristics**

| Symbol   | Parameter                                                                                                  | Value | Unit |
|----------|------------------------------------------------------------------------------------------------------------|-------|------|
| $I_{AR}$ | Avalanche current, repetitive or not repetitive (pulse width limited by $T_{jmax}$ )                       | 1     | A    |
| $E_{AS}$ | Single pulse avalanche energy (starting $T_j=25^{\circ}\text{C}$ , $I_D = I_{AR}$ ; $V_{DD}=50\text{ V}$ ) | 103   | mJ   |

## 2 Electrical characteristics

( $T_C = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

**Table 5. On /off states**

| Symbol        | Parameter                         | Test conditions                                                        | Min. | Typ. | Max.     | Unit          |
|---------------|-----------------------------------|------------------------------------------------------------------------|------|------|----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage    | $V_{GS} = 0, I_D = 1\text{ mA}$                                        | 650  |      |          | V             |
| $I_{DSS}$     | Zero gate voltage drain current   | $V_{GS} = 0, V_{DS} = 650\text{ V}$                                    |      |      | 1        | $\mu\text{A}$ |
|               |                                   | $V_{GS} = 0, V_{DS} = 650\text{ V}, T_C = 125\text{ }^{\circ}\text{C}$ |      |      | 100      | $\mu\text{A}$ |
| $I_{GSS}$     | Gate-body leakage current         | $V_{DS} = 0, V_{GS} = \pm 25\text{ V}$                                 |      |      | $\pm 10$ | $\mu\text{A}$ |
| $V_{GS(th)}$  | Gate threshold voltage            | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$                        | 2    | 3    | 4        | V             |
| $R_{DS(on)}$  | Static drain-source on-resistance | $V_{GS} = 10\text{ V}, I_D = 2.5\text{ A}$                             |      | 0.98 | 1.15     | $\Omega$      |

**Table 6. Dynamic**

| Symbol                     | Parameter                     | Test conditions                                                                                     | Min. | Typ. | Max. | Unit     |
|----------------------------|-------------------------------|-----------------------------------------------------------------------------------------------------|------|------|------|----------|
| $C_{iss}$                  | Input capacitance             | $V_{DS} = 100\text{ V}, f = 1\text{ MHz}, V_{GS} = 0$                                               | -    | 270  | -    | pF       |
| $C_{oss}$                  | Output capacitance            |                                                                                                     | -    | 14.5 | -    | pF       |
| $C_{rss}$                  | Reverse transfer capacitance  |                                                                                                     | -    | 0.8  | -    | pF       |
| $C_{oss\text{ eq.}}^{(1)}$ | Equivalent output capacitance | $V_{DS} = 0\text{ to }520\text{ V}, V_{GS} = 0$                                                     | -    | 108  | -    | pF       |
| $R_G$                      | Intrinsic gate resistance     | $f = 1\text{ MHz open drain}$                                                                       | -    | 7    | -    | $\Omega$ |
| $Q_g$                      | Total gate charge             | $V_{DD} = 520\text{ V}, I_D = 5\text{ A}, V_{GS} = 10\text{ V}$<br>(see <a href="#">Figure 15</a> ) | -    | 9    | -    | nC       |
| $Q_{gs}$                   | Gate-source charge            |                                                                                                     | -    | 2.3  | -    | nC       |
| $Q_{gd}$                   | Gate-drain charge             |                                                                                                     | -    | 4.3  | -    | nC       |

1.  $C_{oss\text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

**Table 7. Switching times**

| Symbol       | Parameter           | Test conditions                                                                                                                                       | Min. | Typ. | Max. | Unit |
|--------------|---------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|------|------|
| $t_{d(on)}$  | Turn-on delay time  | $V_{DD} = 325\text{ V}, I_D = 2.5\text{ A}, R_G = 4.7\text{ }\Omega, V_{GS} = 10\text{ V}$<br>(see <a href="#">Figure 14</a> and <a href="#">19</a> ) | -    | 8    | -    | ns   |
| $t_r$        | Rise time           |                                                                                                                                                       | -    | 20   | -    | ns   |
| $t_{d(off)}$ | Turn-off delay time |                                                                                                                                                       | -    | 30   | -    | ns   |
| $t_f$        | Fall time           |                                                                                                                                                       | -    | 20   | -    | ns   |

Table 8. Source drain diode

| Symbol          | Parameter                     | Test conditions                                                                                                                                              | Min. | Typ. | Max. | Unit          |
|-----------------|-------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|------|---------------|
| $I_{SD}$        | Source-drain current          |                                                                                                                                                              | -    |      | 5    | A             |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) |                                                                                                                                                              | -    |      | 20   | A             |
| $V_{SD}^{(2)}$  | Forward on voltage            | $I_{SD} = 5\text{ A}$ , $V_{GS} = 0$                                                                                                                         | -    |      | 1.6  | V             |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$<br>$V_{DD} = 60\text{ V}$ (see <a href="#">Figure 19</a> )                                        | -    | 275  |      | ns            |
| $Q_{rr}$        | Reverse recovery charge       |                                                                                                                                                              | -    | 1.62 |      | $\mu\text{C}$ |
| $I_{RRM}$       | Reverse recovery current      |                                                                                                                                                              | -    | 11.8 |      | A             |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$<br>$V_{DD} = 60\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$<br>(see <a href="#">Figure 19</a> ) | -    | 430  |      | ns            |
| $Q_{rr}$        | Reverse recovery charge       |                                                                                                                                                              | -    | 2.54 |      | $\mu\text{C}$ |
| $I_{RRM}$       | Reverse recovery current      |                                                                                                                                                              | -    | 11.9 |      | A             |

1. Pulse width limited by safe operating area.

2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

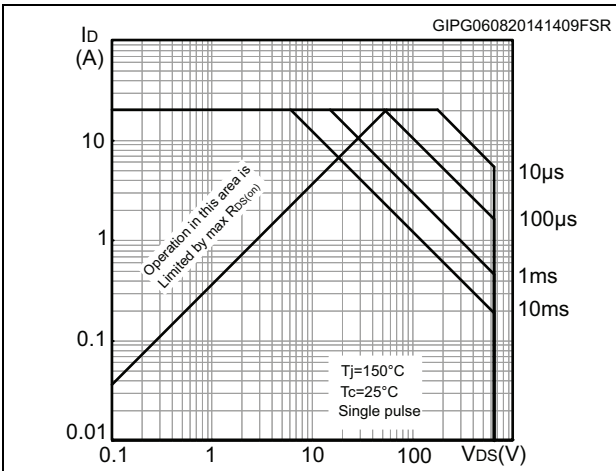


Figure 3. Thermal impedance

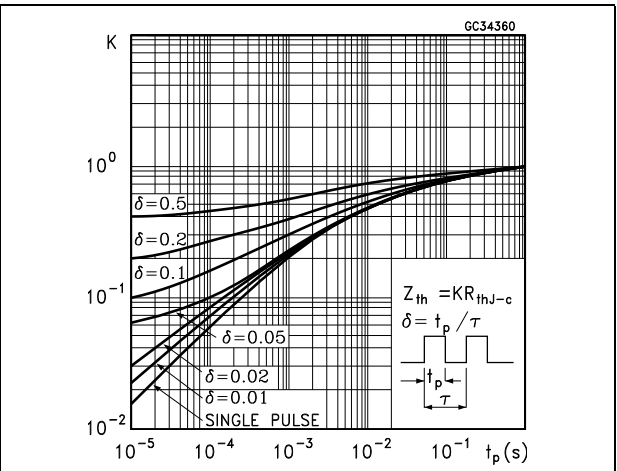


Figure 4. Output characteristics

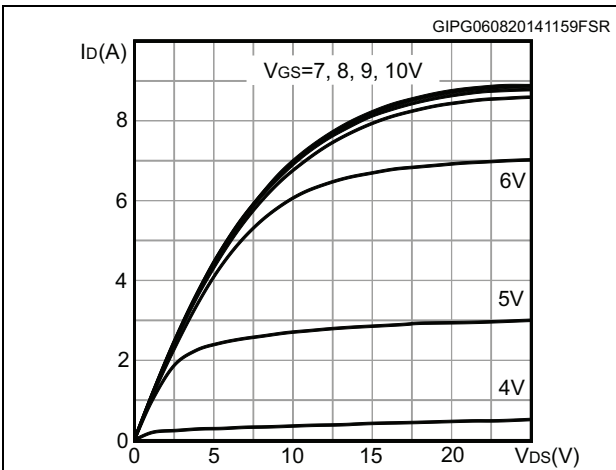


Figure 5. Transfer characteristics

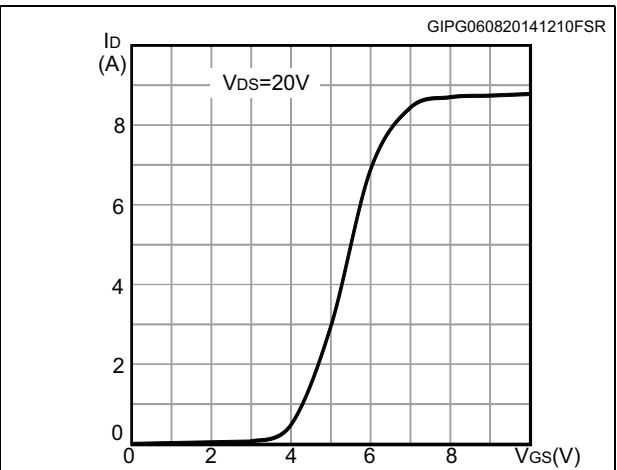


Figure 6. Gate charge vs gate-source voltage

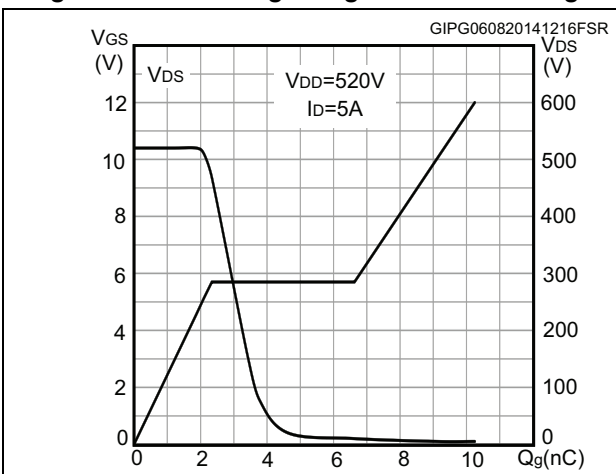


Figure 7. Static drain-source on-resistance

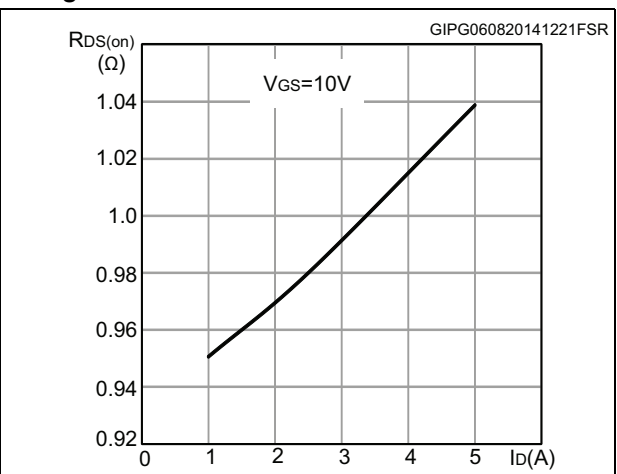


Figure 8. Capacitance variations

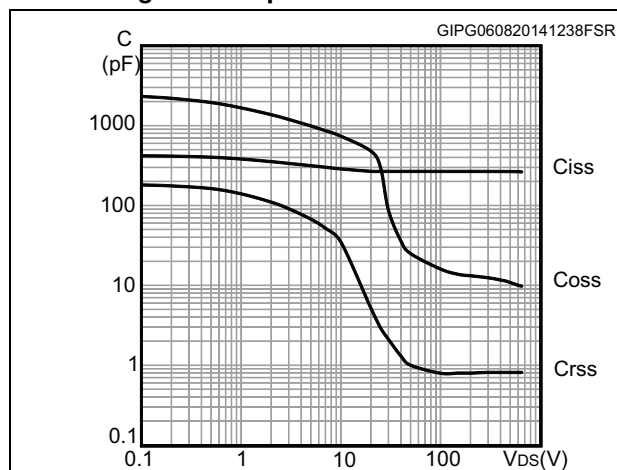


Figure 9. Output capacitance stored energy

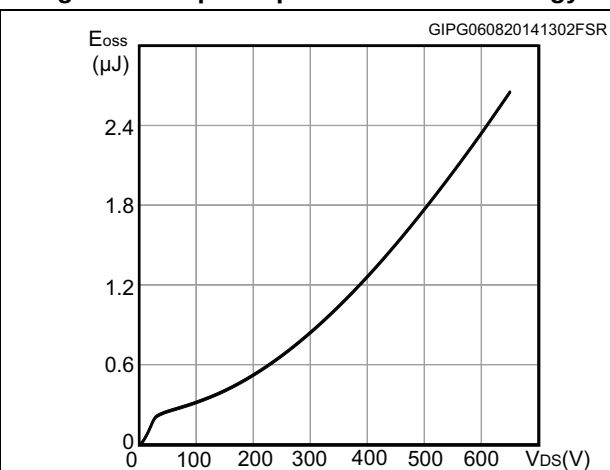


Figure 10. Normalized gate threshold voltage vs temperature

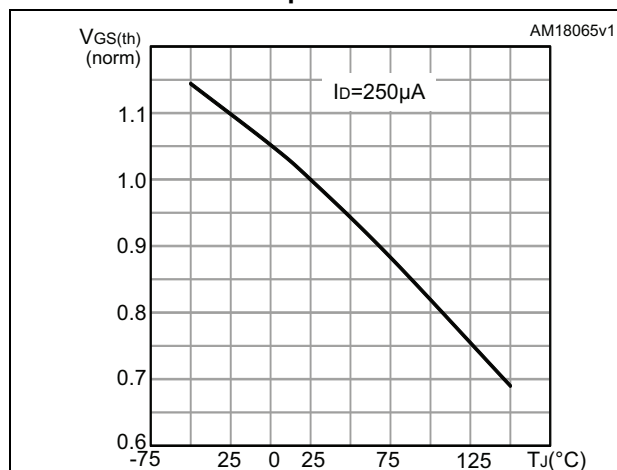


Figure 11. Normalized on-resistance vs temperature

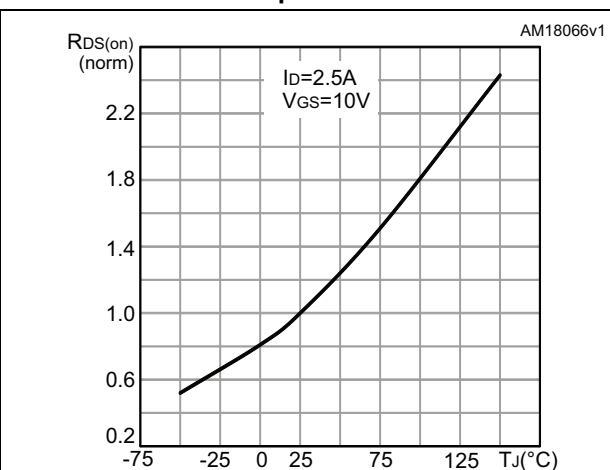
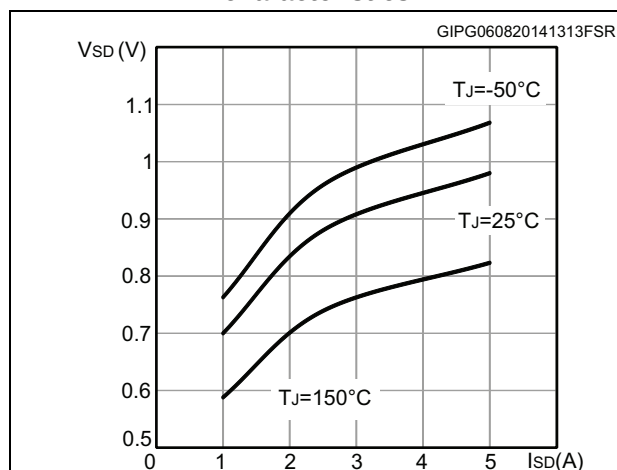
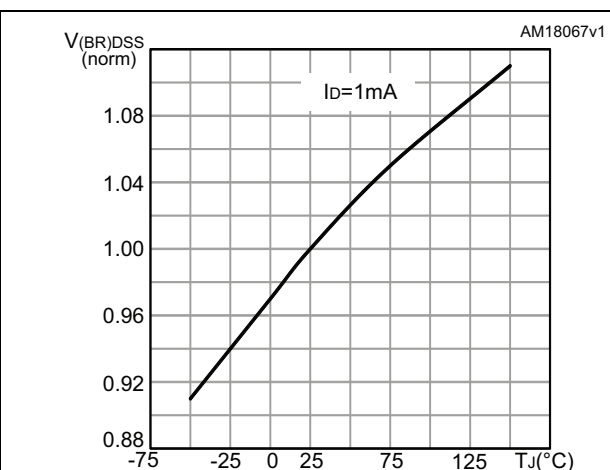
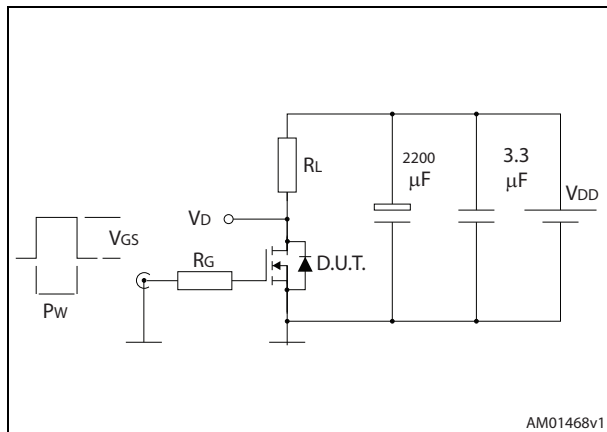


Figure 12. Source-drain diode forward characteristics

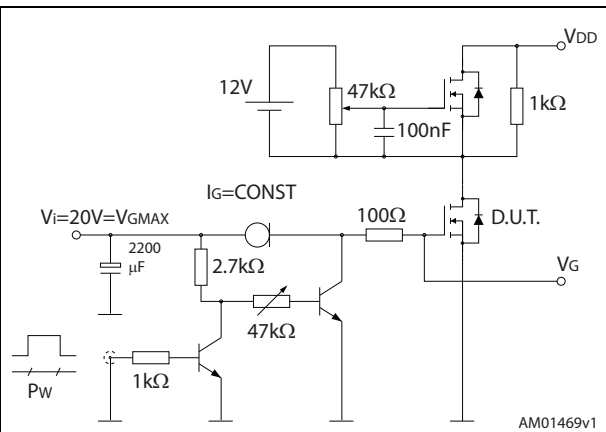
Figure 13. Normalized  $V_{(BR)DSS}$  vs temperature

### 3 Test circuits

**Figure 14. Switching times test circuit for resistive load**



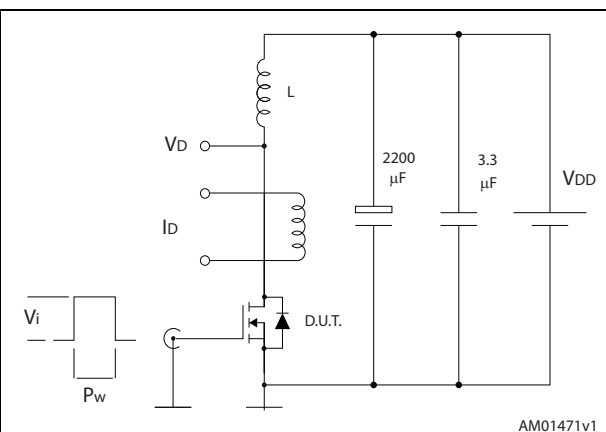
**Figure 15. Gate charge test circuit**



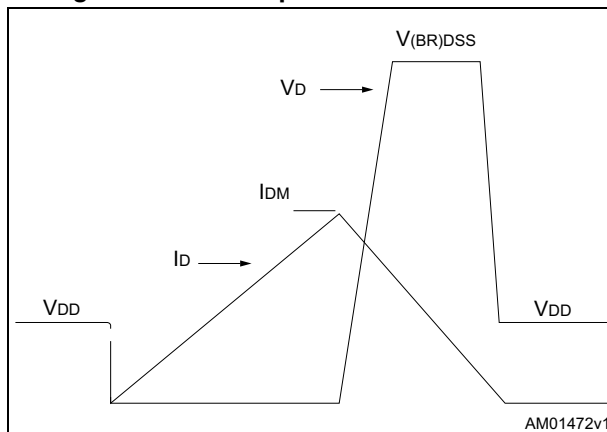
**Figure 16. Test circuit for inductive load switching and diode recovery times**



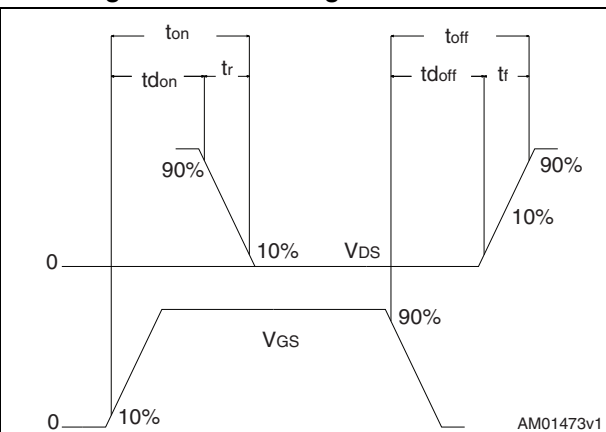
**Figure 17. Unclamped inductive load test circuit**



**Figure 18. Unclamped inductive waveform**



**Figure 19. Switching time waveform**



## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 DPAK (TO-252) type A package information

Figure 20. DPAK (TO-252) type A package outline

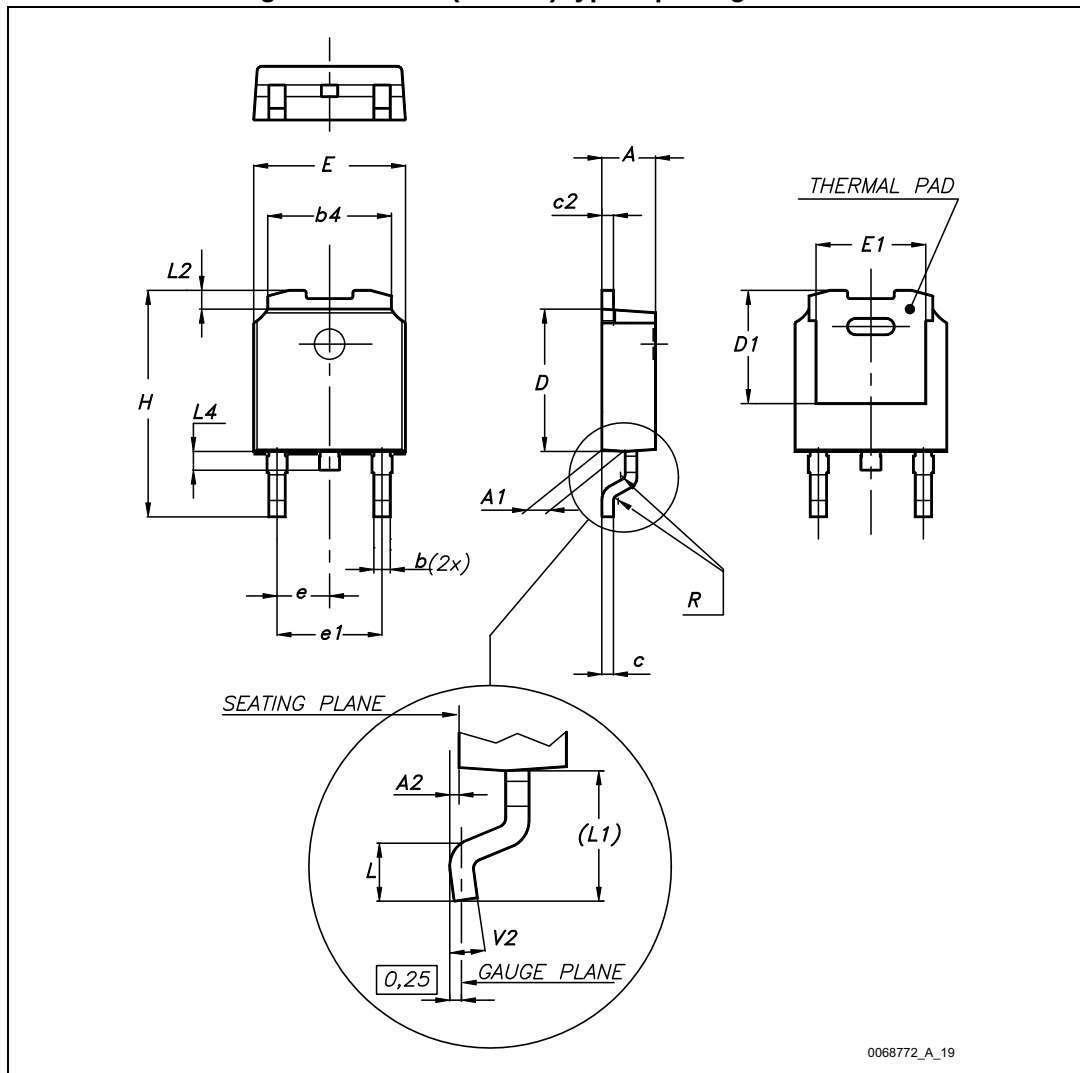


Table 9. DPAK (TO-252) type A package mechanical data

| Dim. | mm   |      |       |
|------|------|------|-------|
|      | Min. | Typ. | Max.  |
| A    | 2.20 |      | 2.40  |
| A1   | 0.90 |      | 1.10  |
| A2   | 0.03 |      | 0.23  |
| b    | 0.64 |      | 0.90  |
| b4   | 5.20 |      | 5.40  |
| c    | 0.45 |      | 0.60  |
| c2   | 0.48 |      | 0.60  |
| D    | 6.00 |      | 6.20  |
| D1   | 4.95 | 5.10 | 5.25  |
| E    | 6.40 |      | 6.60  |
| E1   | 4.60 | 4.70 | 4.80  |
| e    | 2.16 | 2.28 | 2.40  |
| e1   | 4.40 |      | 4.60  |
| H    | 9.35 |      | 10.10 |
| L    | 1.00 |      | 1.50  |
| (L1) | 2.60 | 2.80 | 3.00  |
| L2   | 0.65 | 0.80 | 0.95  |
| L4   | 0.60 |      | 1.00  |
| R    |      | 0.20 |       |
| V2   | 0°   |      | 8°    |

## 4.2 DPAK (TO-252) type C package information

Figure 21. DPAK (TO-252) type C package outline

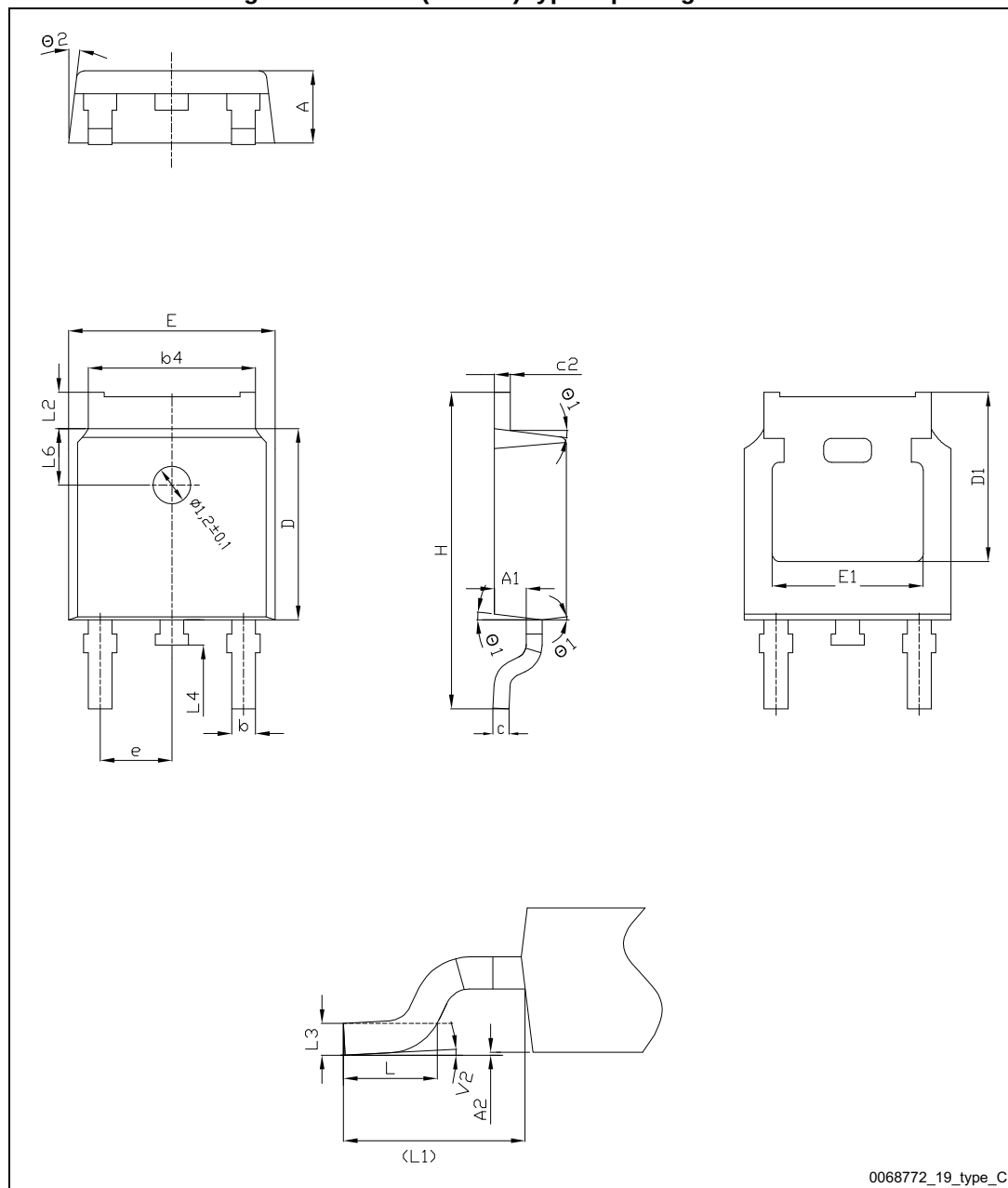
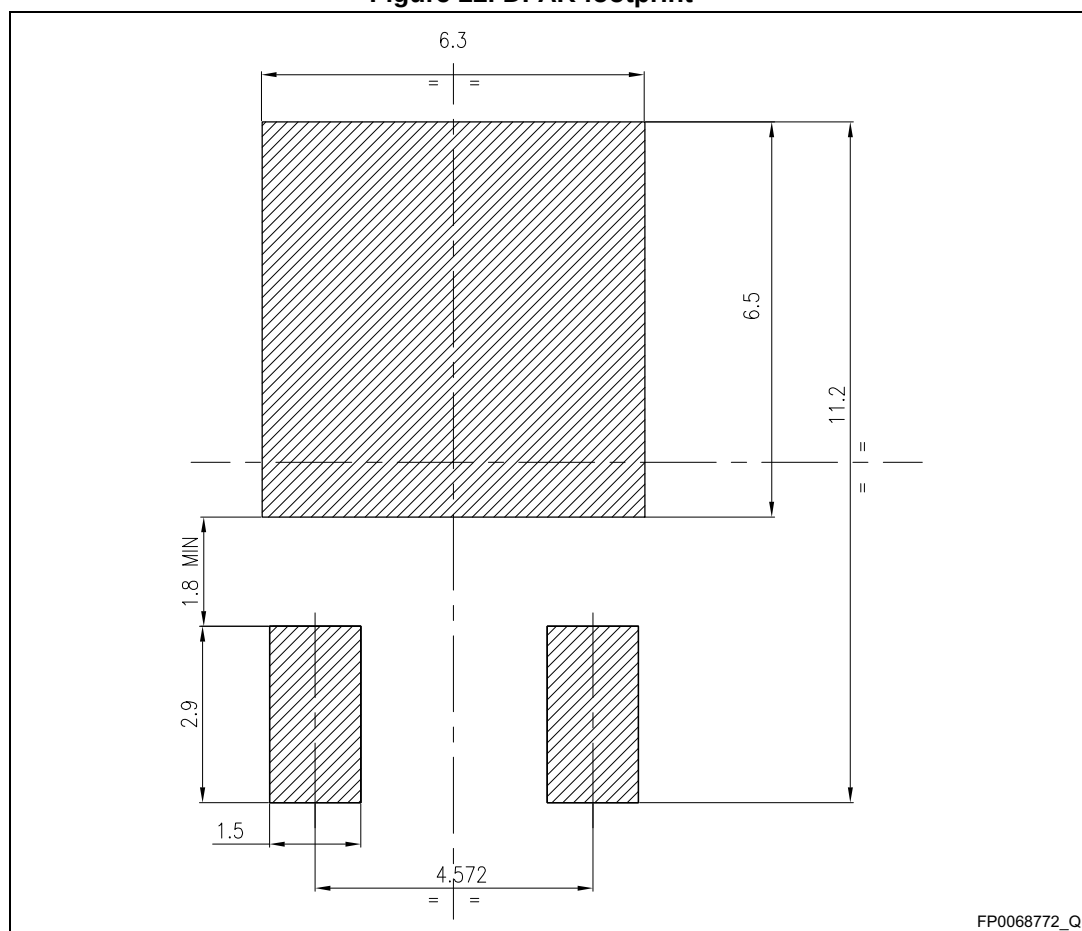


Table 10. DPAK (TO-252) type C package mechanical data

| Dim. | mm       |       |       |
|------|----------|-------|-------|
|      | Min.     | Typ.  | Max.  |
| A    | 2.20     | 2.30  | 2.38  |
| A1   | 0.90     | 1.01  | 1.10  |
| A2   | 0.00     |       | 0.10  |
| b    | 0.72     |       | 0.85  |
| b4   | 5.13     | 5.33  | 5.46  |
| c    | 0.47     |       | 0.60  |
| c2   | 0.47     |       | 0.60  |
| D    | 6.00     | 6.10  | 6.20  |
| D1   | 5.25     |       |       |
| E    | 6.50     | 6.60  | 6.70  |
| e    | 2.186    | 2.286 | 2.386 |
| E1   | 4.70     |       |       |
| H    | 9.80     | 10.10 | 10.40 |
| L    | 1.40     | 1.50  | 1.70  |
| L1   | 2.90 REF |       |       |
| L2   | 0.90     |       | 1.25  |
| L3   | 0.51 BSC |       |       |
| L4   | 0.60     | 0.80  | 1.00  |
| L6   | 1.80 BSC |       |       |
| Ø1   | 5°       | 7°    | 9°    |
| Ø2   | 5°       | 7°    | 9°    |
| V2   | 0°       |       | 8°    |

Figure 22. DPAK footprint (a)



a. All dimensions are in millimeters

5 Packaging mechanical data

Figure 23. Tape for DPAK (TO-252)

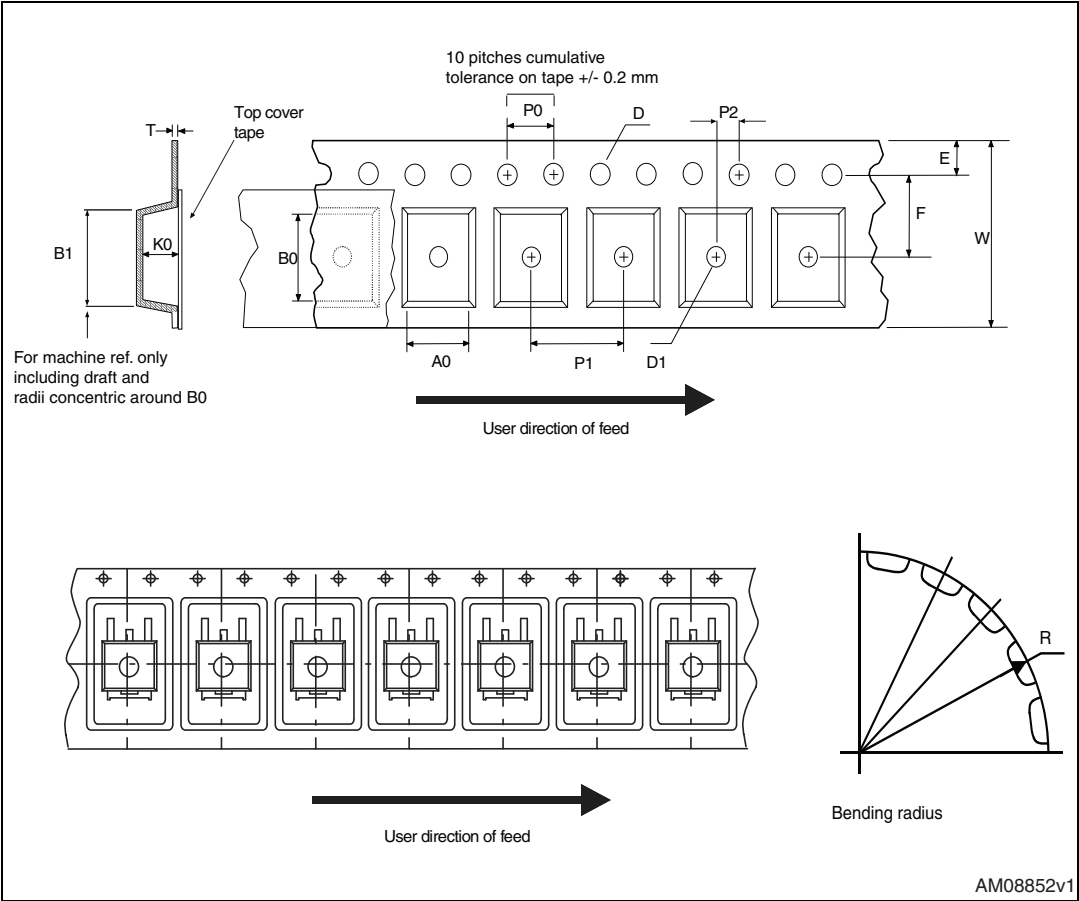


Figure 24. Reel for DPAK (TO-252)

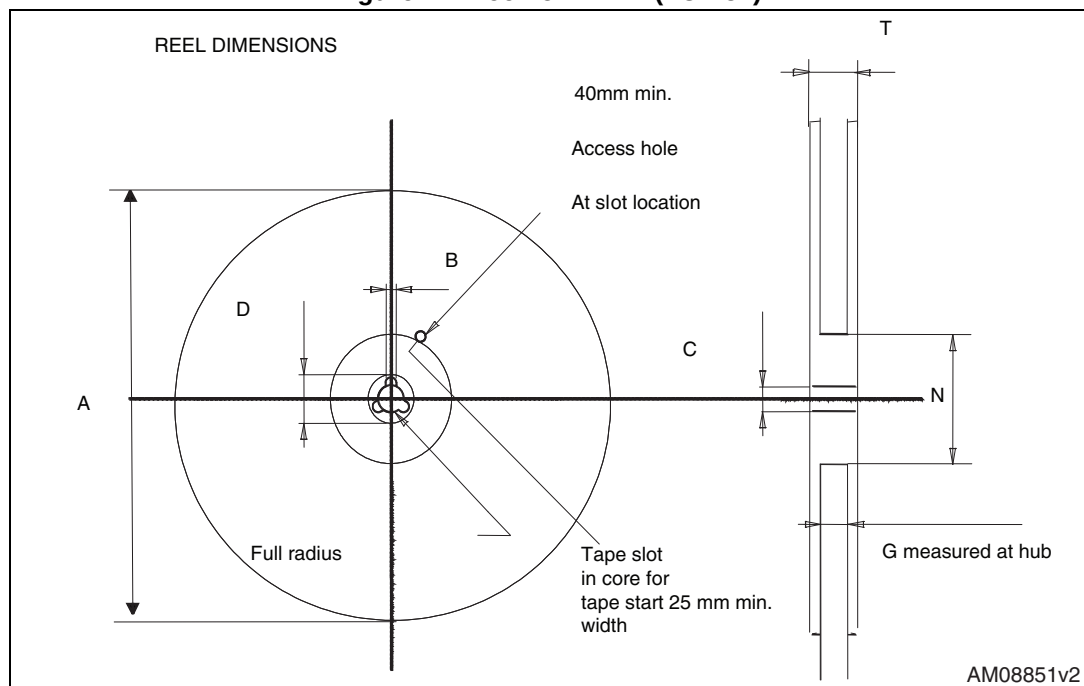


Table 11. DPAK (TO-252) tape and reel mechanical data

| Tape |      |      | Reel      |      |      |
|------|------|------|-----------|------|------|
| Dim. | mm   |      | Dim.      | mm   |      |
|      | Min. | Max. |           | Min. | Max. |
| A0   | 6.8  | 7    | A         |      | 330  |
| B0   | 10.4 | 10.6 | B         | 1.5  |      |
| B1   |      | 12.1 | C         | 12.8 | 13.2 |
| D    | 1.5  | 1.6  | D         | 20.2 |      |
| D1   | 1.5  |      | G         | 16.4 | 18.4 |
| E    | 1.65 | 1.85 | N         | 50   |      |
| F    | 7.4  | 7.6  | T         |      | 22.4 |
| K0   | 2.55 | 2.75 |           |      |      |
| P0   | 3.9  | 4.1  | Base qty. |      | 2500 |
| P1   | 7.9  | 8.1  | Bulk qty. |      | 2500 |
| P2   | 1.9  | 2.1  |           |      |      |
| R    | 40   |      |           |      |      |
| T    | 0.25 | 0.35 |           |      |      |
| W    | 15.7 | 16.3 |           |      |      |

## 6 Revision history

**Table 12. Document revision history**

| Date        | Revision | Changes                                                                                                                   |
|-------------|----------|---------------------------------------------------------------------------------------------------------------------------|
| 07-Aug-2014 | 1        | First release.                                                                                                            |
| 06-May-2015 | 2        | Document status promoted from preliminary to production data.<br>Updated <a href="#">Section 4: Package information</a> . |

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